

[54] THERMALLY-EFFICIENT HEAT SINK FOR ELECTRONIC DEVICES

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[\*\*] Term: 14 Years

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[52] U.S. Cl. .... D13/23

[58] Field of Search ..... D13/23; 174/16 HS; 357/81; 165/80.1, 80.2, 80.3, 185

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[57] CLAIM

The ornamental design for a thermally-efficient heat sink for electronic devices, substantially as shown.

DESCRIPTION

FIG. 1 is a perspective view of a thermally-efficient heat sink for electronic devices showing my new design;

FIG. 2 is a front elevational view of the same heat sink, the rear elevational view being the same;

FIG. 3 is a side elevational view thereof, looking toward the right side of the heat sink as it is shown in FIG. 1, the side elevational view thereof looking toward the left side of the heat sink as it is shown in FIG. 1 being the same;

FIG. 4 is a top plan view thereof; and  
FIG. 5 is a bottom plan view thereof.

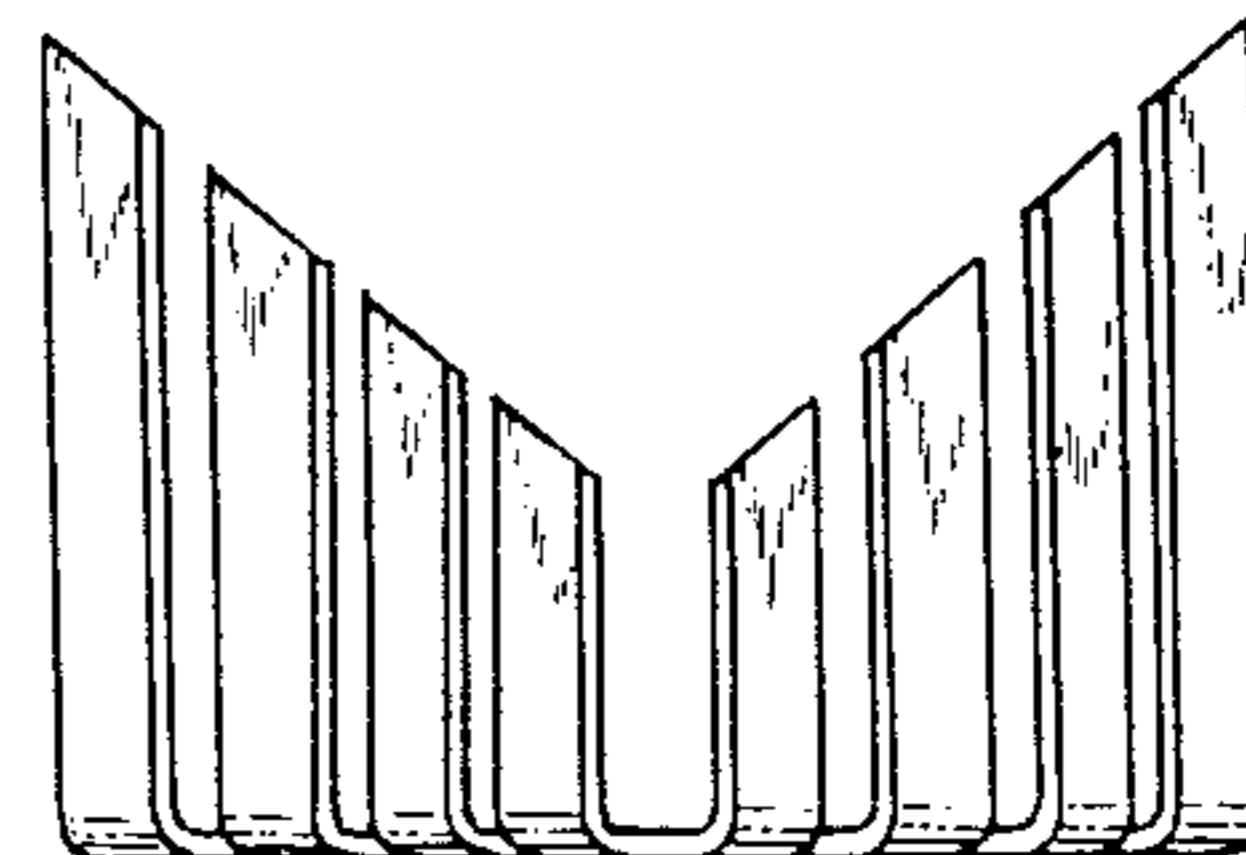
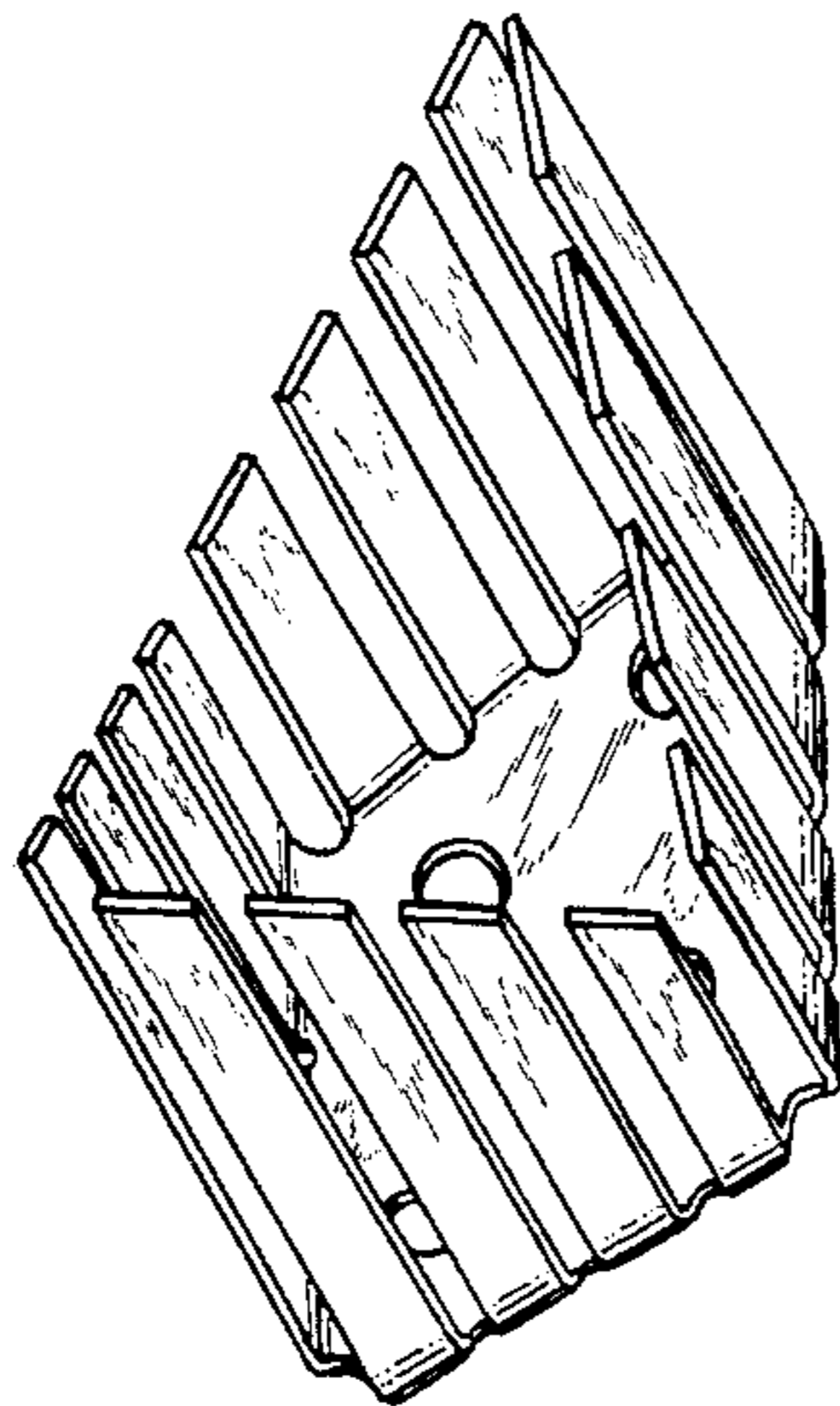


FIG. 1

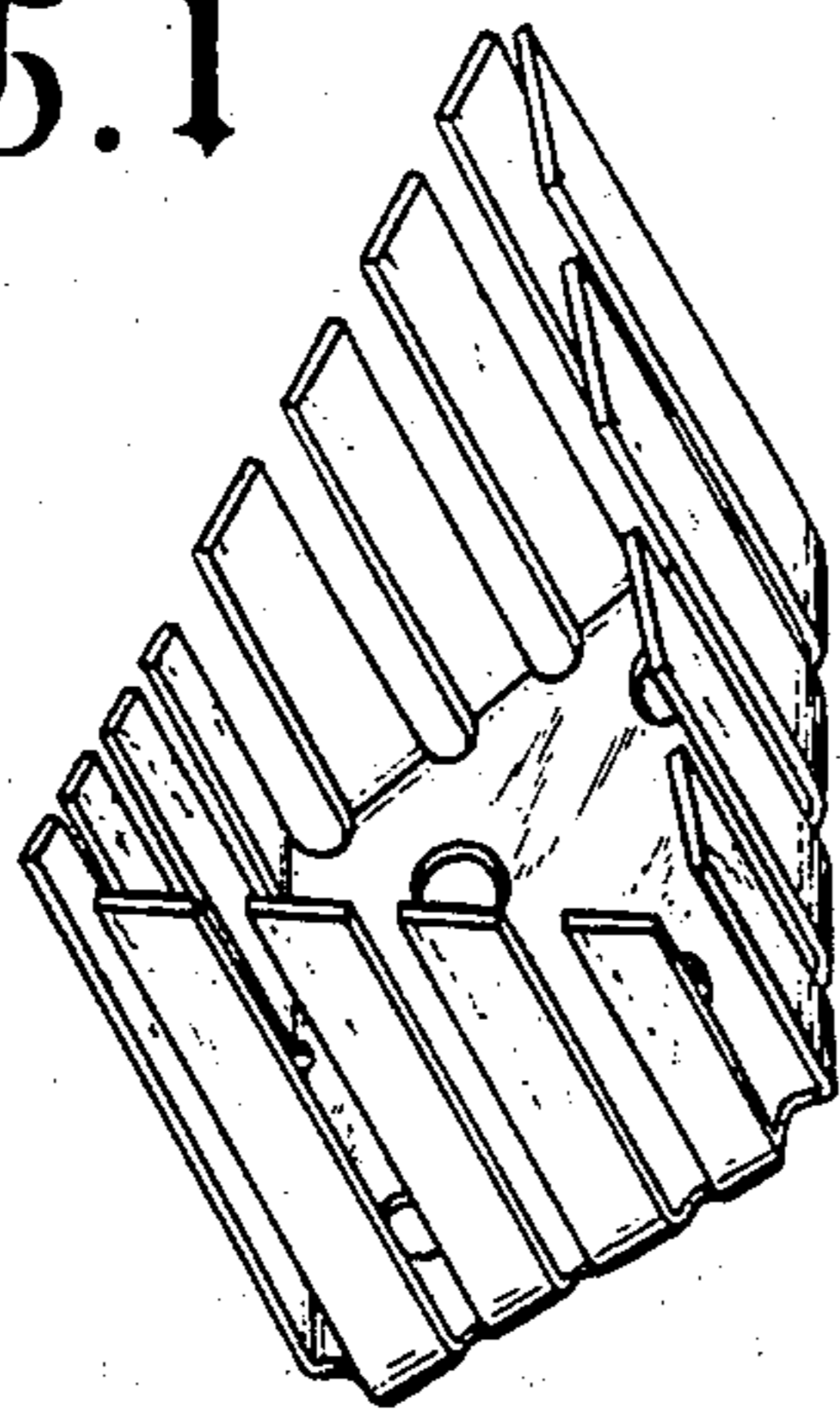


FIG. 2

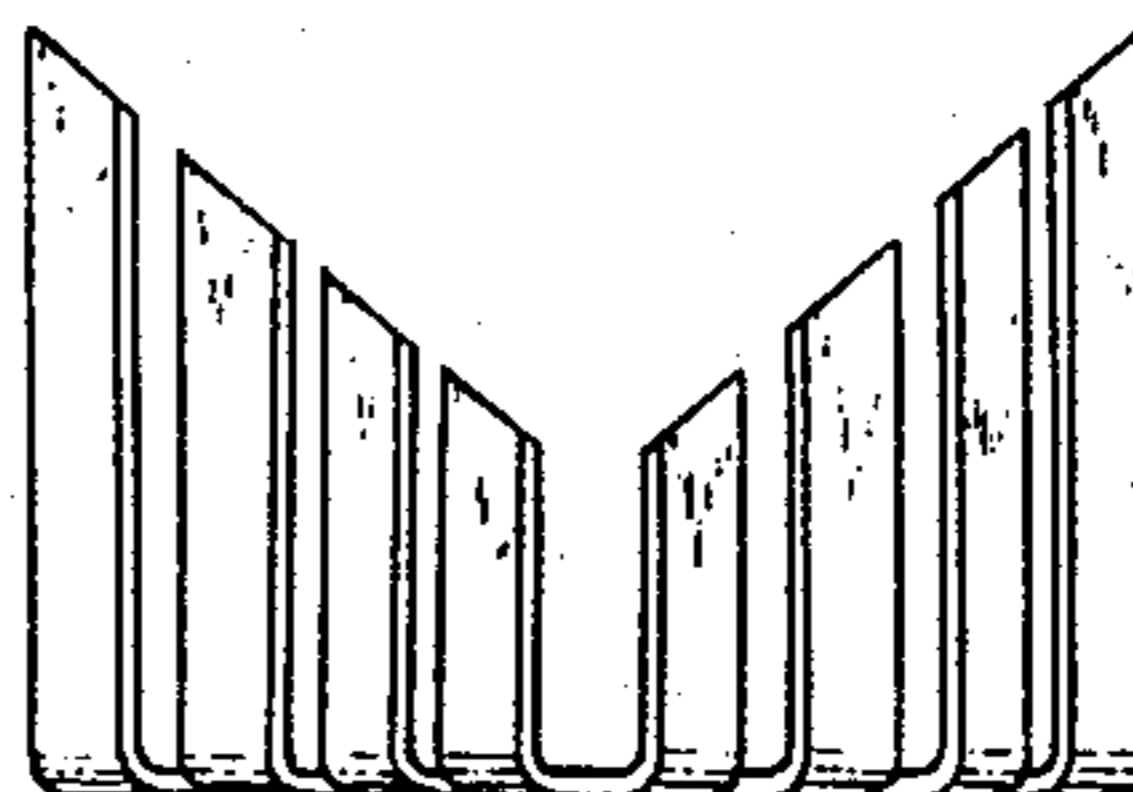


FIG. 3

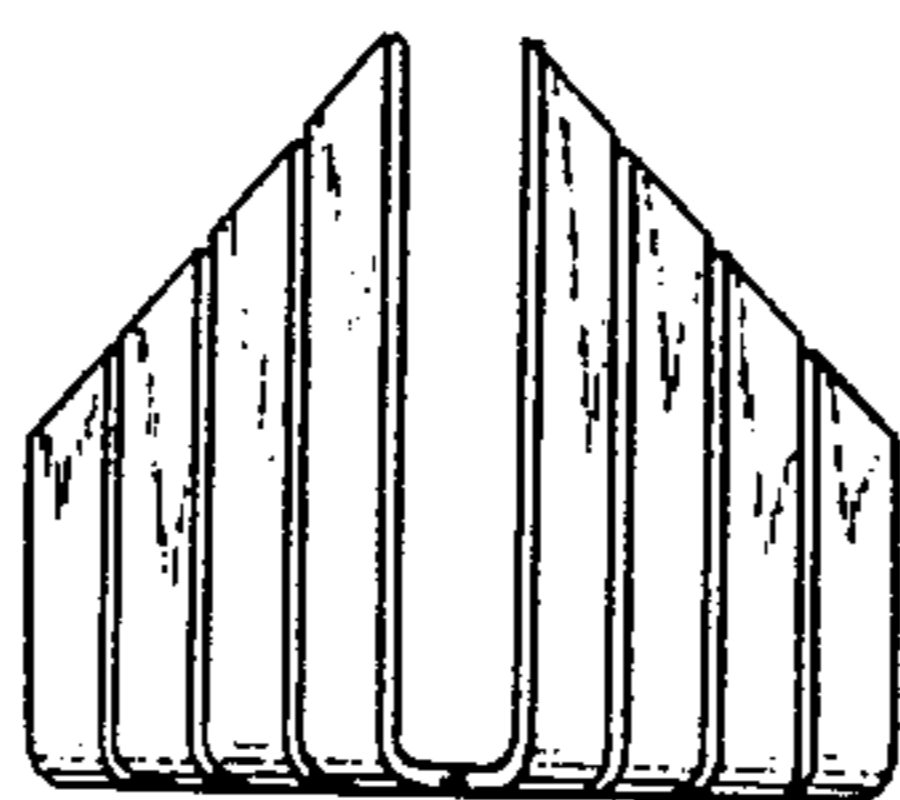


FIG. 4

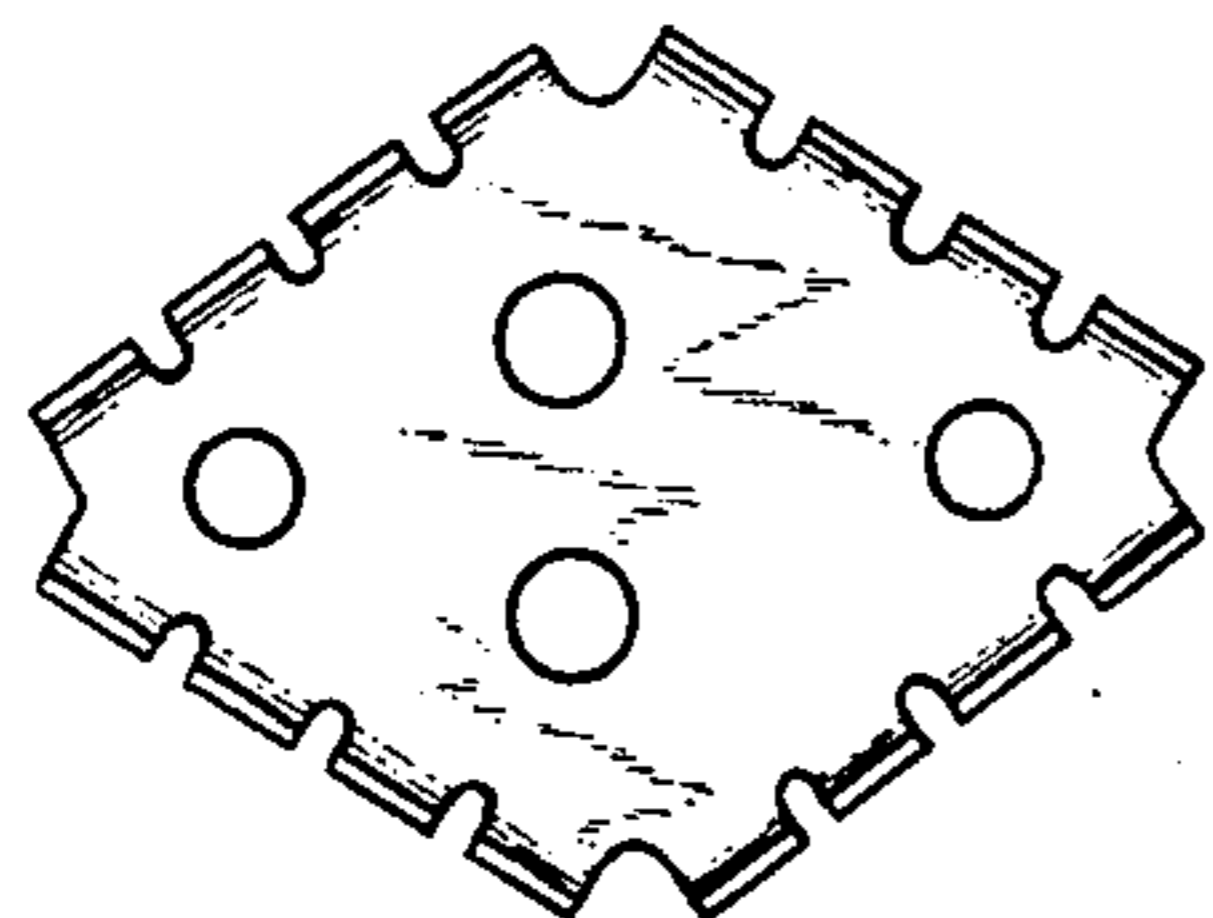


FIG. 5

